Material Composition Declar © Copyright 2005. IPC, Bannockburn, international and Pan-American copyri				urn, Illinois. All rights reserved under both			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
IPC Web Site for Information on IP http://www.ipc.org/IPC-175x				PC-1752 Standard Form Type * Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					erials and l	ials and Mfg Information				
Supplier	r Informa	tion															
Company name*			Company un	Company unique ID				Unique ID Authority					Response Date*				
onsemi												2024-0	2024-04-19				
Contact Name			Title - Contact				Phone - Contact*					Email	Email - Contact*				
Product-I	Env-Stewar	ds		Product Enviro Compliance			NA NA					Produ	Product-Env-Stewards@onsemi.com				
Authorize	Authorized Representative*			Title - Representative				Phone - Representative*					Email	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA					Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Item						Effective	Date	Version	N	Manufacturing Site		Weigh	nt*	UOM	Unit Type		
	NCP508N		MT28TBG 50 MA LDO				2024-04-	-19		N	MY1		6.05		mg	Each	
Manufacturing Process Information																	
Terminal Plating / Grid Array Material To		erminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Pro		ocess Body Temperature Max Time at Peak		ak Temper	Temperature Number		f Reflow Cycles				
SnAgCu			U Alloy 1		1		260			C	30		seconds 3				
Comments																	
level 1 - maximum time at peak temperature during soldering is 10-30 seconds																	
For more	information	regarding material con	position	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction that such information is true and correction to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.4	mg	Supplier	Silicon (Si)	7440-21-3		0.4	mg
Die Attach	0.1	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.032	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.068	mg
Lead Frame	2.41	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0036	mg
			Supplier	Silicon (Si)	7440-21-3		0.0157	mg
			В	Nickel (Ni)	7440-02-0		0.0723	mg
			Supplier	Copper (Cu)	7440-50-8		2.3184	mg
Mold Compound-Black	2.98	mg		Epoxy Phenol Resin	proprietary data		0.3129	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.6671	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0044	mg
			В	Nickel (Ni)	7440-02-0		0.0649	mg
			Supplier	Gold (Au)	7440-57-5		0.0007	mg
Wire Bond - Au	0.09	mg	Supplier	Gold (Au)	7440-57-5		0.09	mg